



# Planar Edgeless Silicon Detectors for the TOTEM Experiment

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**on behalf of the TOTEM collaboration**

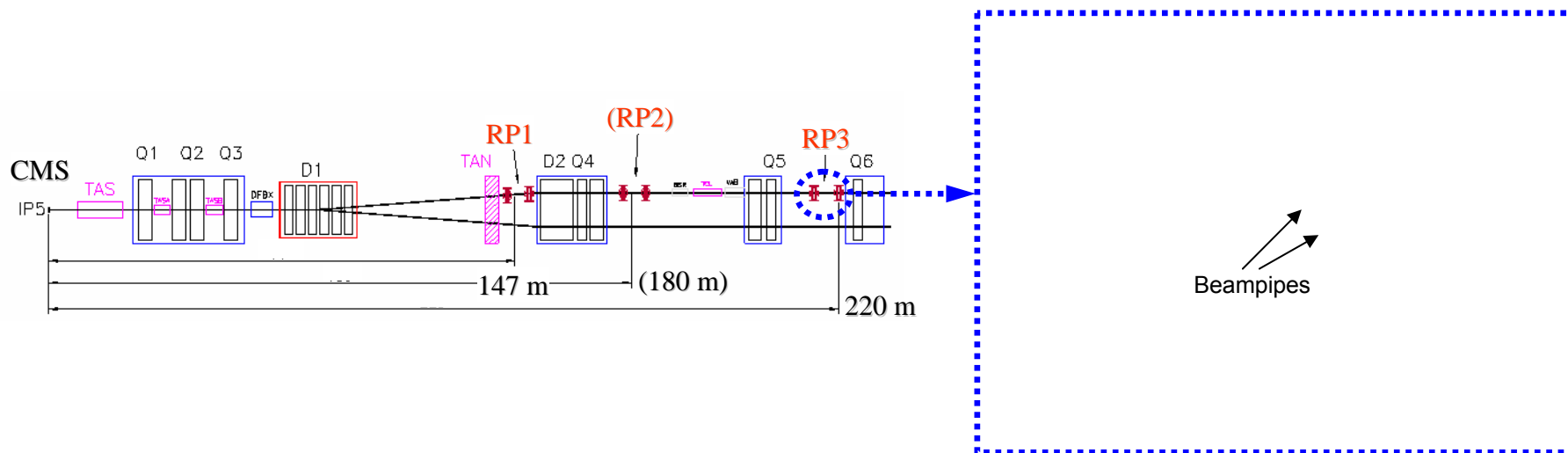


# Outline

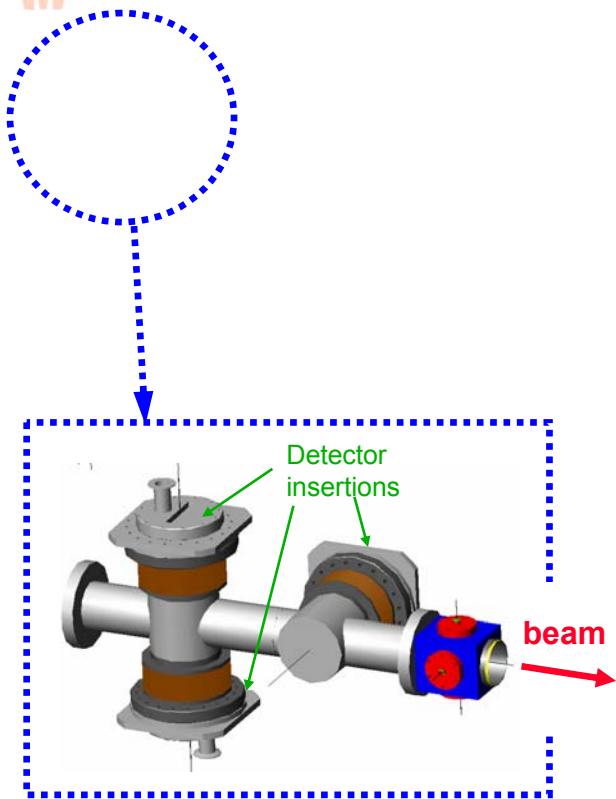
- ◆ **1. The TOTEM experiment**
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# 1. The TOTEM experiment

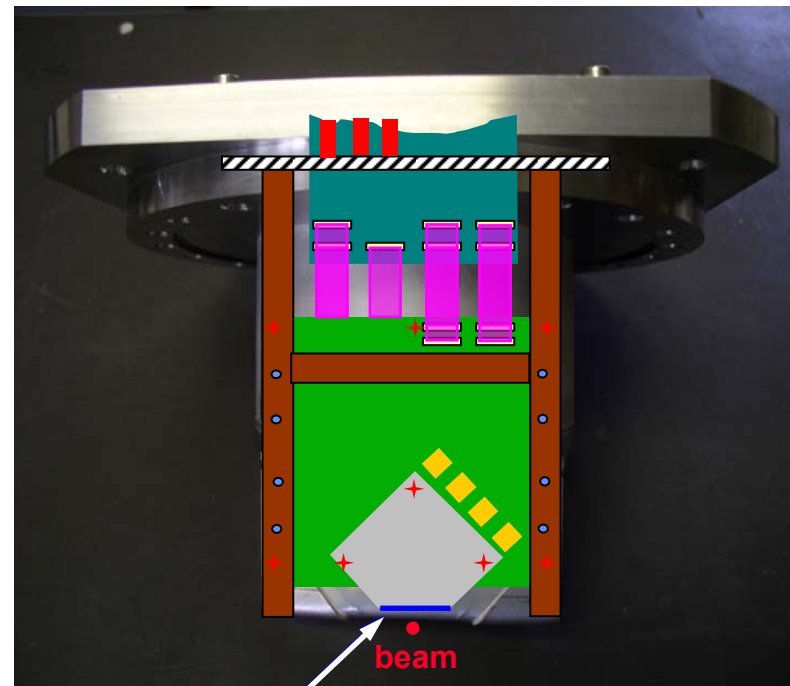
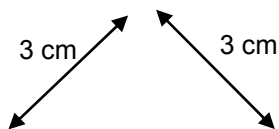
In order to determine the total cross section of pp interactions with 1% uncertainty at  $\sqrt{s} = 14$  TeV, the TOTEM experiment will detect leading protons scattered in angles of microradians. This is achieved using tracking detectors with a minimized insensitive edge not exceeding  $50 \mu\text{m}$  inserted into Roman Pots (RP).



# 1.1 Roman Pot Stations



Tracking Detectors



Dead area to be minimized

The tracking detectors must be placed as close as possible to the 10  $\sigma$  envelope of the beam

# 1.3 Requirements on the “edgeless” tracking detectors

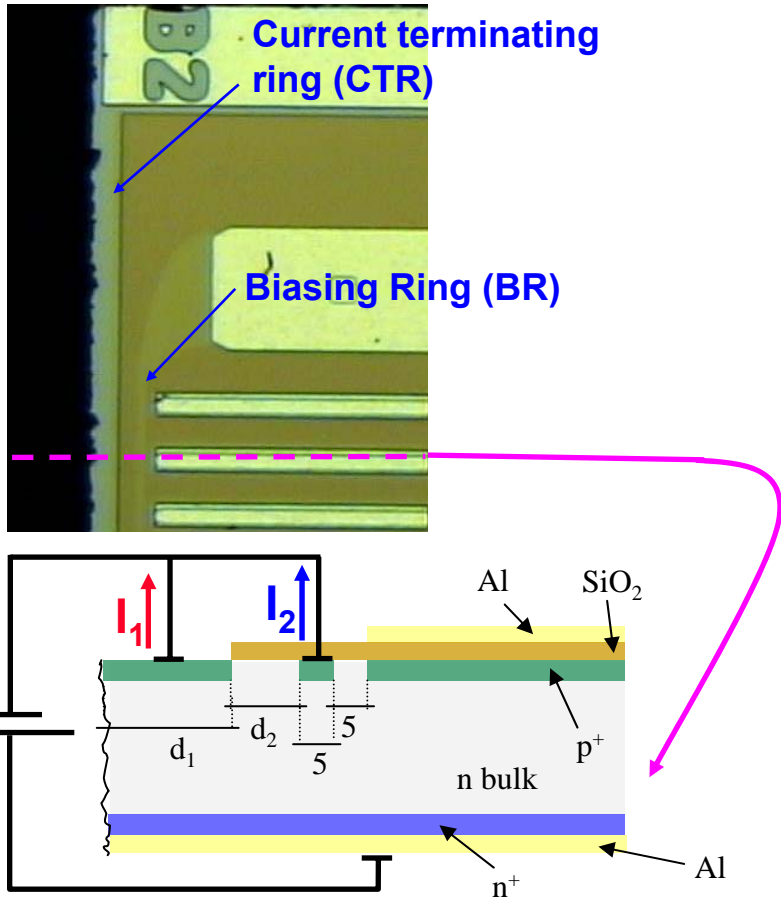
The detectors must fulfill the following requirements:

- ◆ Spatial resolution of 10-20  $\mu\text{m}$
- ◆ Charge collection time not exceeding 25 ns
- ◆ Radiation hardness up to  $10^{14}$  “n”/cm<sup>2</sup>
- ◆ Operational temperature not below -20°C
- ◆ Inactive edge not exceeding 50  $\mu\text{m}$

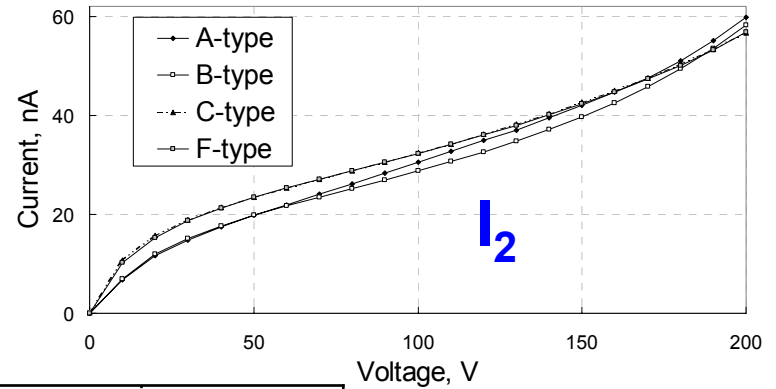
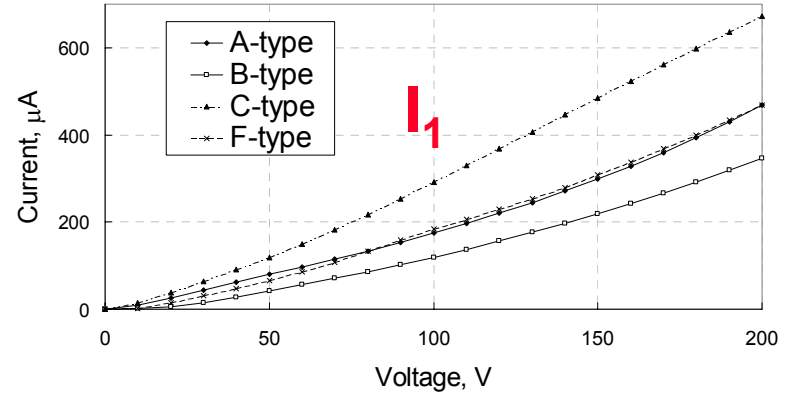
Two different technologies are being considered:

- ◆ planar “edgeless” detectors
- ◆ planar “edgeless” detectors with 3D edges

# 2. Basic Principle of Planar Edgeless Detectors



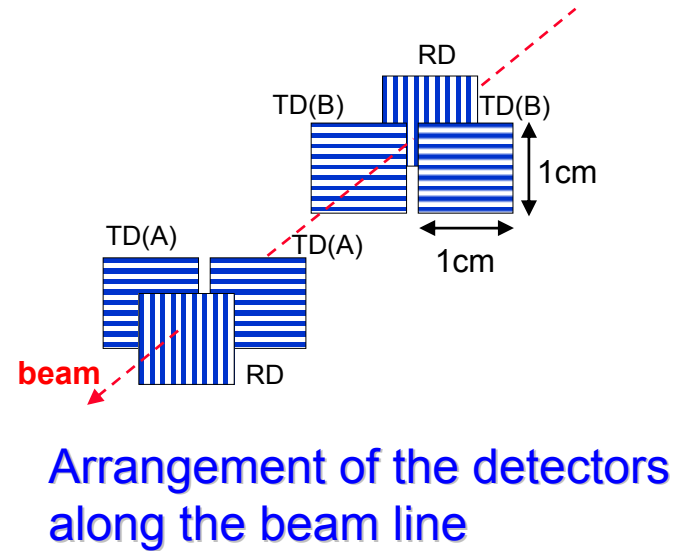
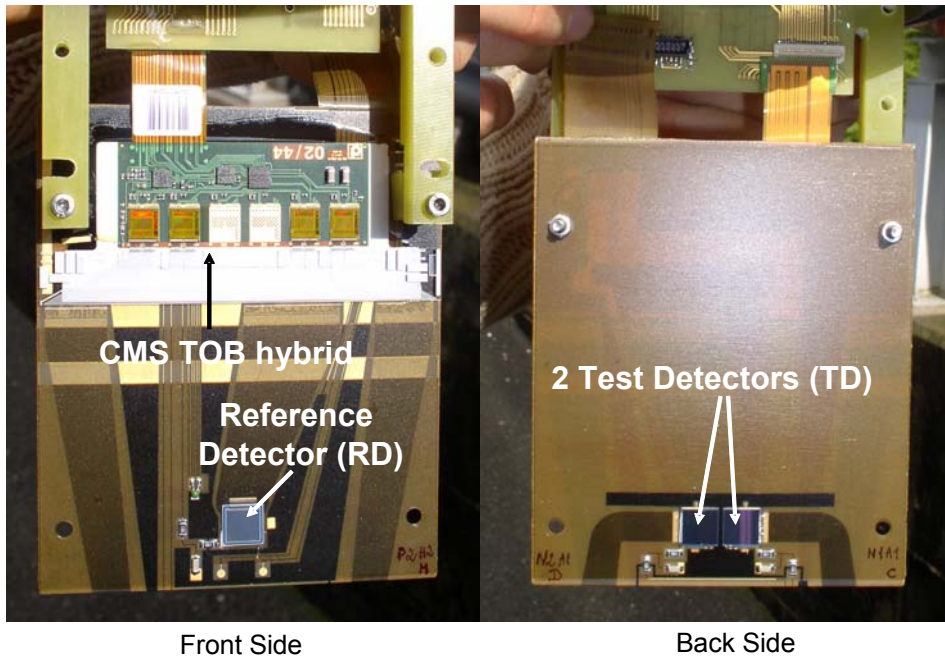
TOTEM Technical Design Report  
 CERN-LHCC-2004-002 (2004)  
 G. Ruggiero et al., "Planar edgeless Silicon Detectors for the TOTEM experiment",  
 Accepted for publication in IEEE Trans. Nucl. on Sci.



Type	$d_1+d_2$ ( $\mu\text{m}$ )
A	20+10
B	20+20
C	40+10
F	60+20

**This design allows full separation of surface and bulk generated current**

# 2.1 Small size detector test setup

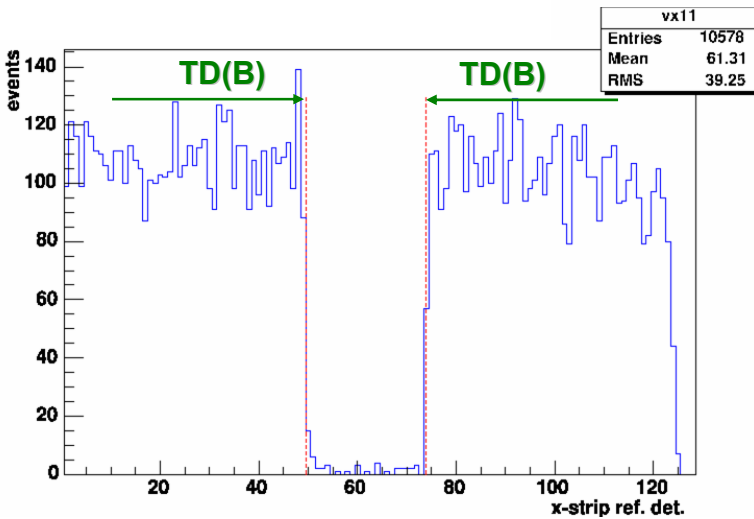
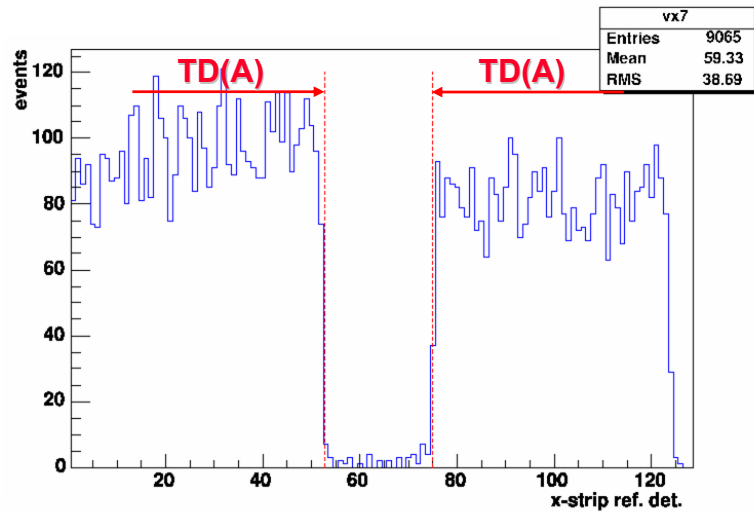


Module with detectors and readout electronics:

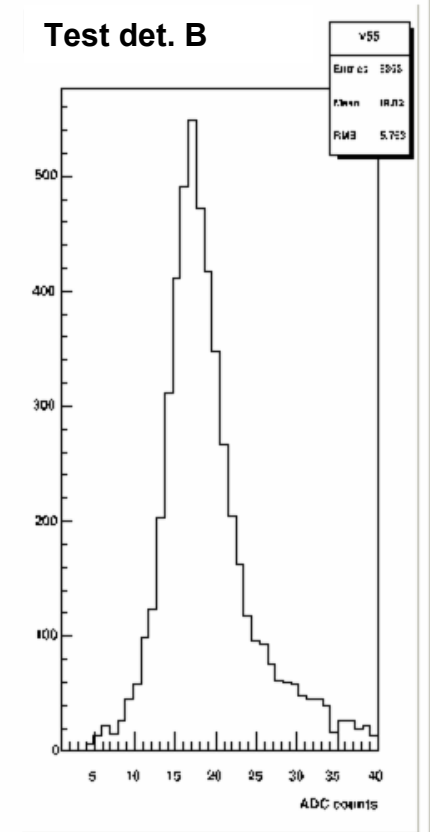
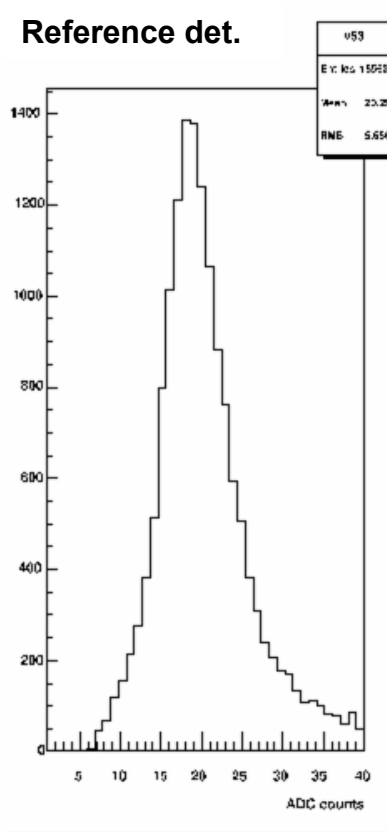
- Test Detectors placed edge-to-edge, reference detector pitch  $50\ \mu\text{m}$
- APV25 chips used for read-out

**The small size detectors were tested in a high energy muon beam at CERN**

# 2.2 Small size detector performance



Signal-to-noise  $\approx 18$  for a detector thickness of  $300\mu\text{m}$

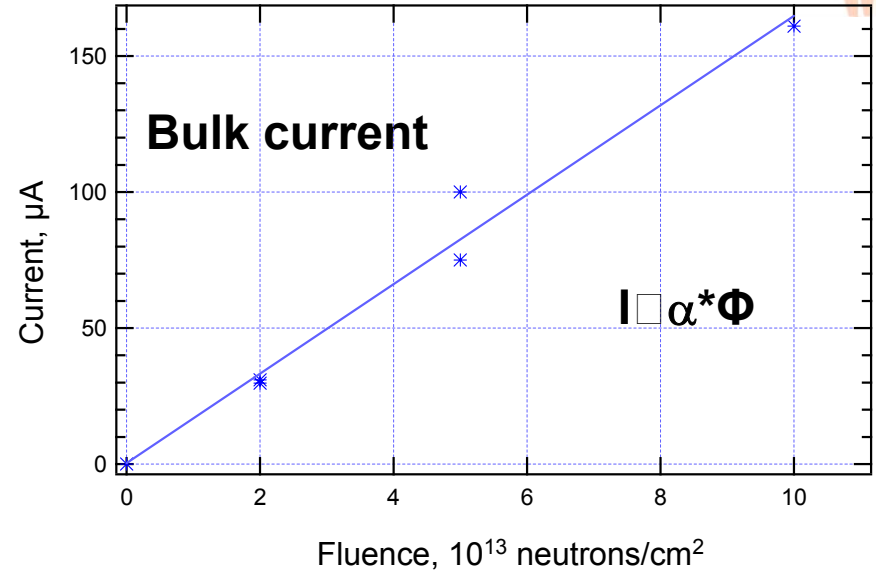
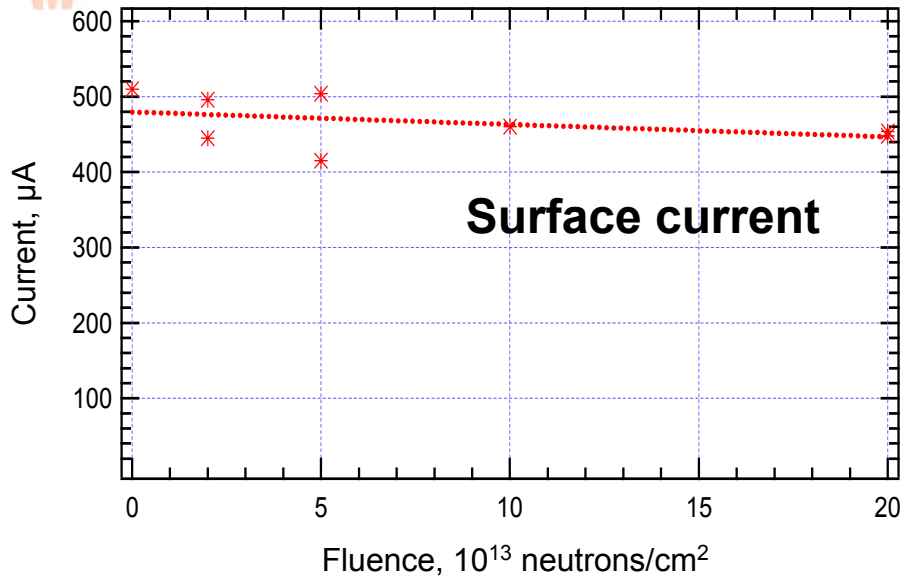


**Detectors fully sensitive up to  $60\mu\text{m}$  from the edge**



# 2.3 Radiation Tests on Edgeless Planar Detectors

All detectors fully depleted



## Studies on irradiated silicon detectors:

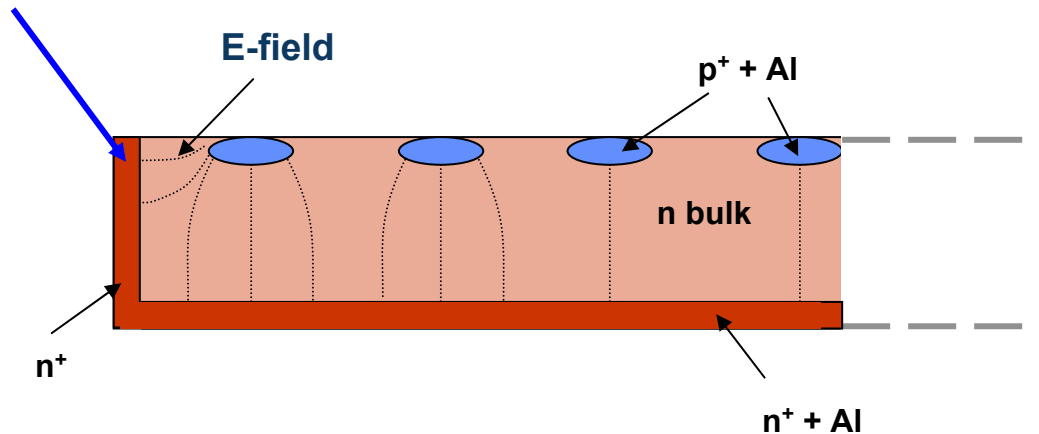
- ◆ No increase in the surface current with fluence (as expected)
- ◆ Bulk current increases with fluence in agreement with what is observed in standard planar detectors

$$\text{(damage factor } \alpha = \frac{\text{Current}}{\text{Volume} \times \text{Fluence}} = 5 \times 10^{-17} \text{ A/cm)}$$

**These data suggest a radiation hardness for the Edgeless Planar detectors equal to the standard planar detectors up to  $10^{14}$  “n”/cm $^2$**

# 3. Basic principle of planar 3D detectors

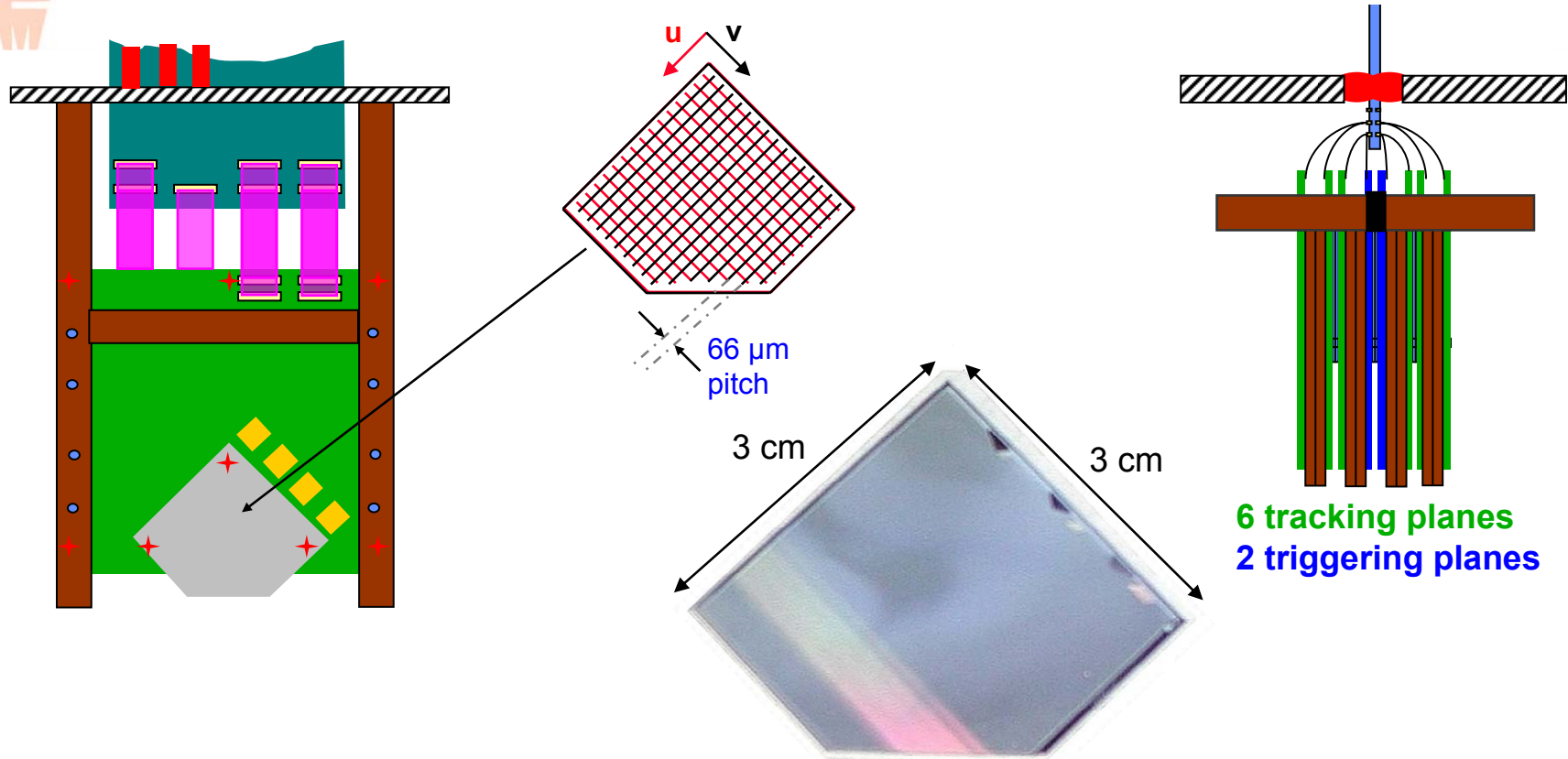
Traditional planar detector + deep etched edge filled with doped polysilicon



*TOTEM Technical Design Report*  
CERN-LHCC-2004-002 (2004)  
C.J. Kenney et al.,  
IEEE Trans. on Nucl. Sci. 48 (2) 189 (2003)

## Smaller dead area than for planar technology

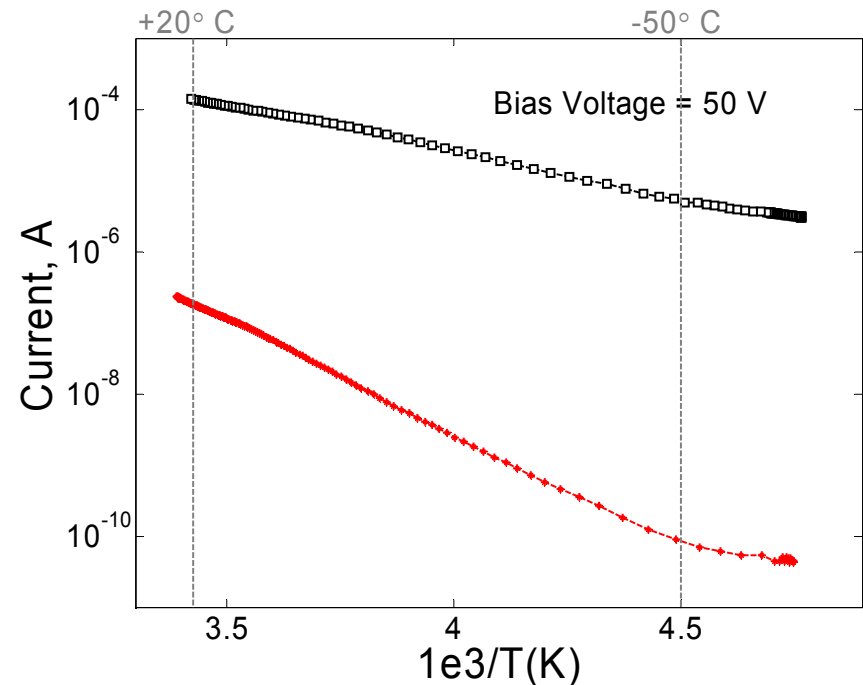
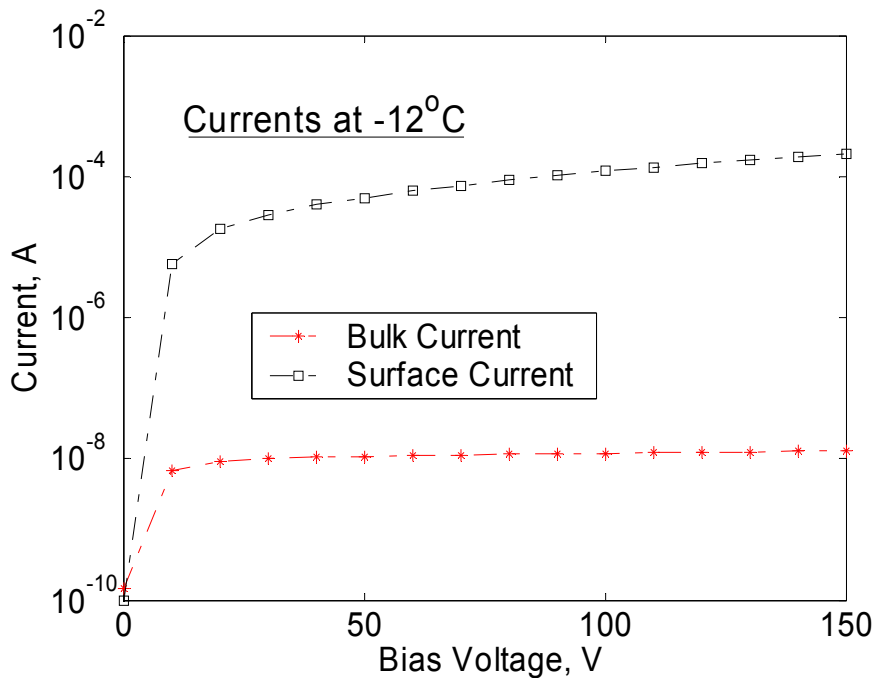
# 4. Final size Edgeless Planar Detectors



**Final size edgeless detectors were produced and tested in 2004 :**

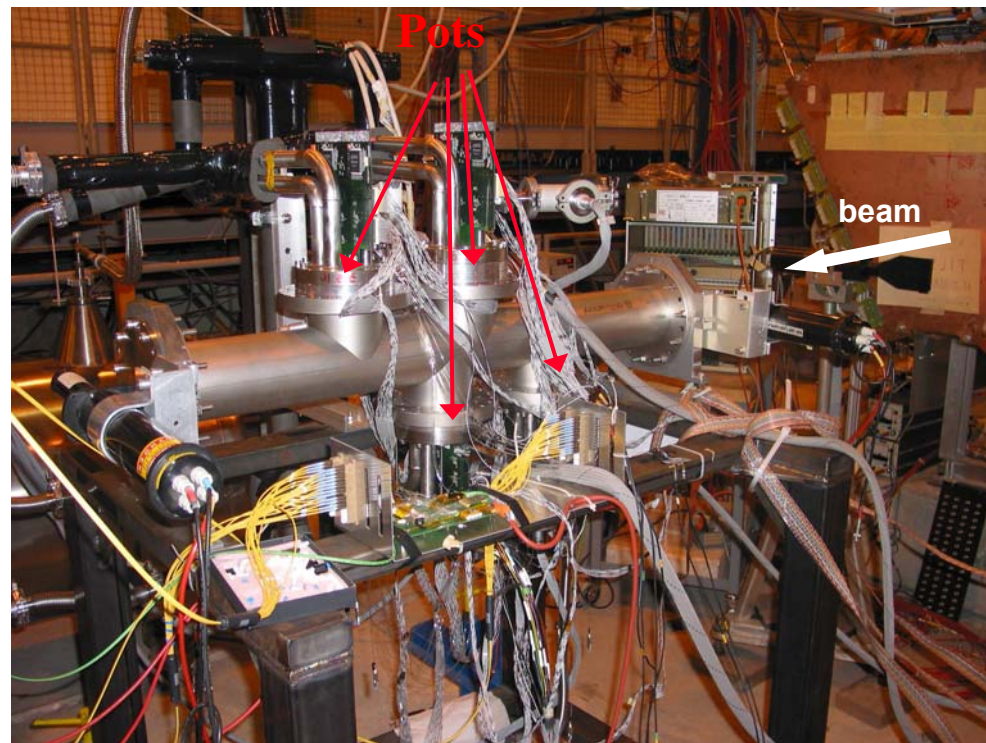
- ◆ In a fixed target experiment with high energy muons
- ◆ In a coasting beam experiment with high energy protons

# 4.1 Temperature performance of the final size detectors

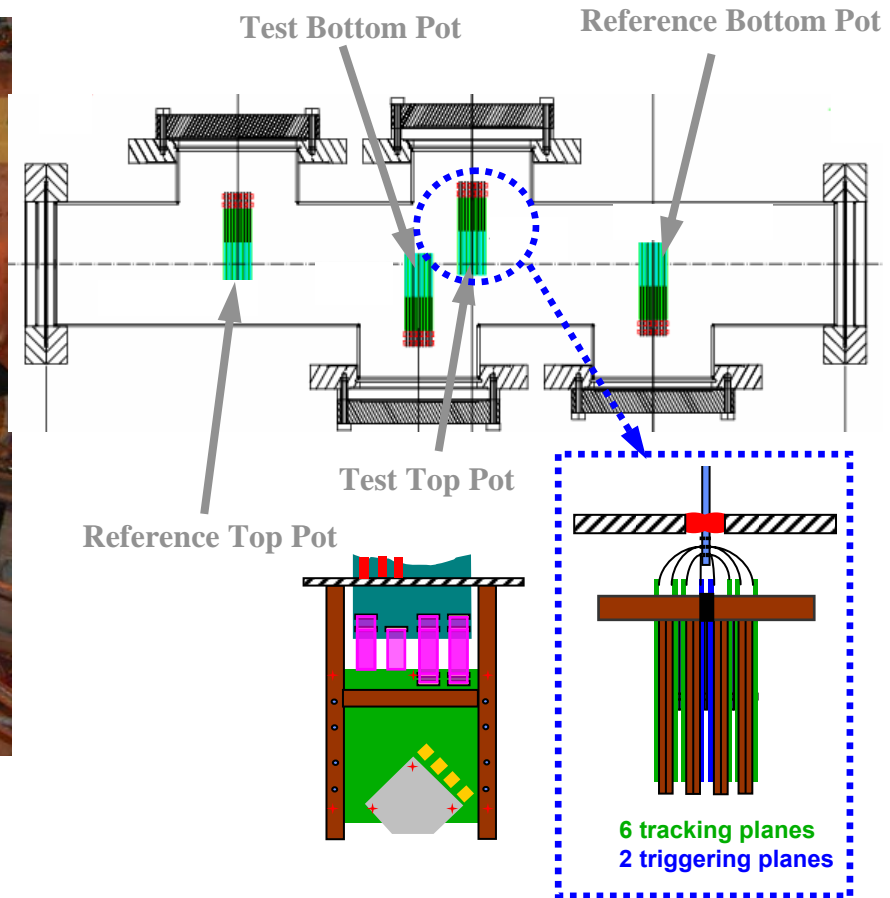


**Surface current less reduced than bulk current by cooling**

# 4.2 Detector performance test in fixed target experiment

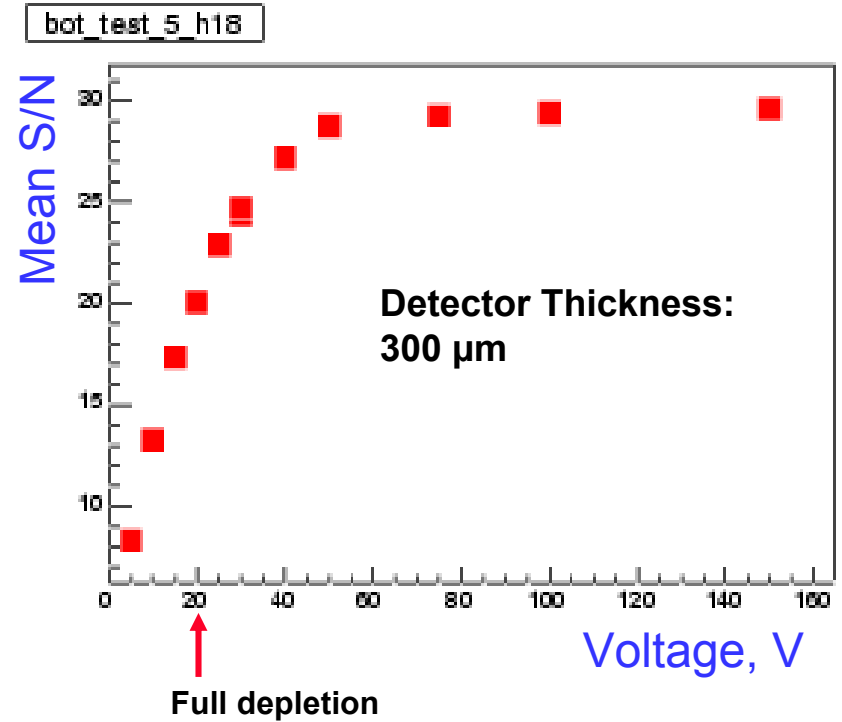
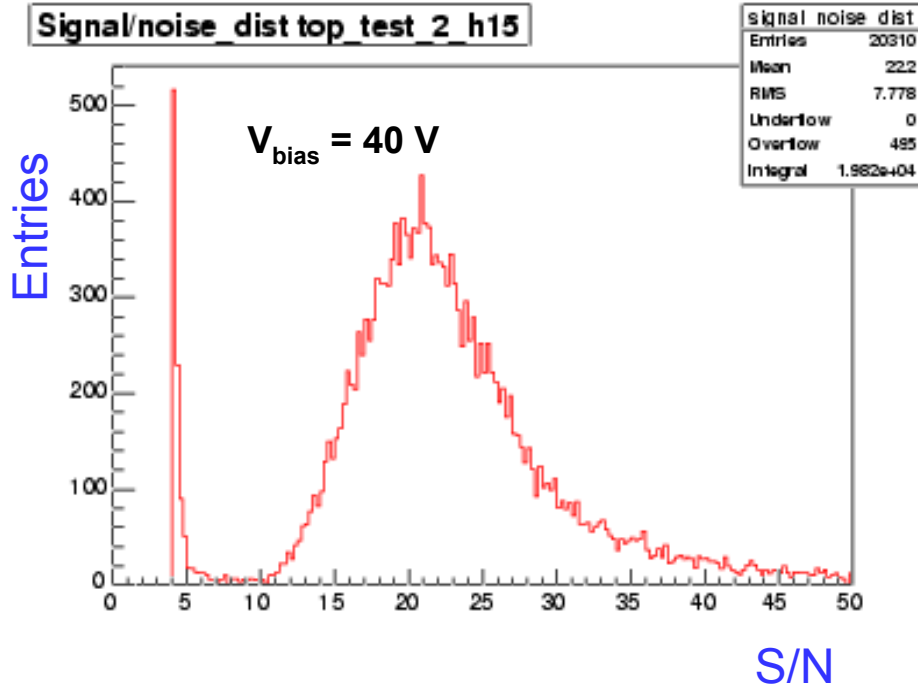


Set-up used in a high energy (120 GeV) muon beam



- ◆ **Triggering: VFAT digital chip and/or scintillators**
- ◆ **Tracking readout: APV25 analog chip**

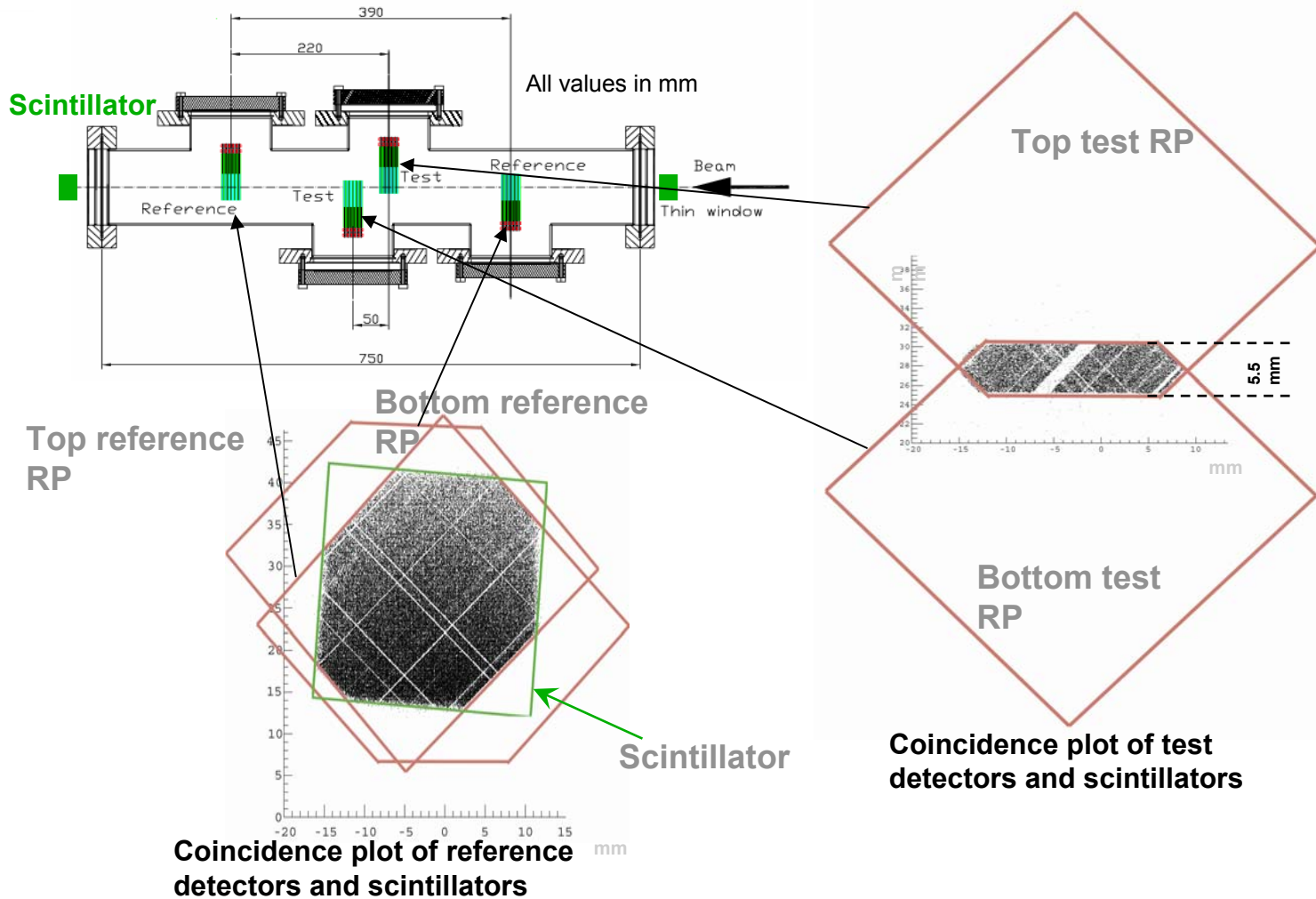
# 4.3 Detector response



**Faster collection time with increasing voltage, signal-to-noise ratio allows high signal selection efficiency**



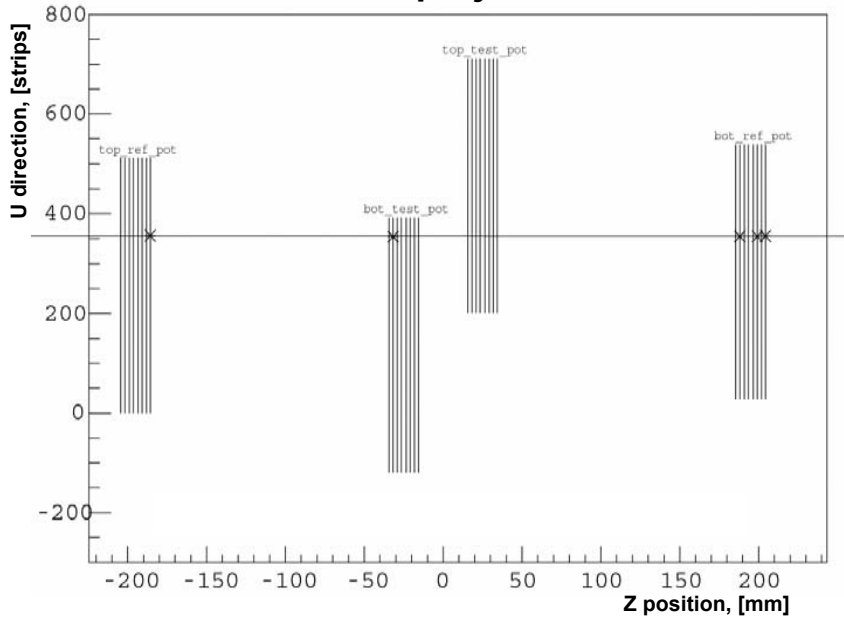
# 4.4 Hit distributions of reference and test detectors



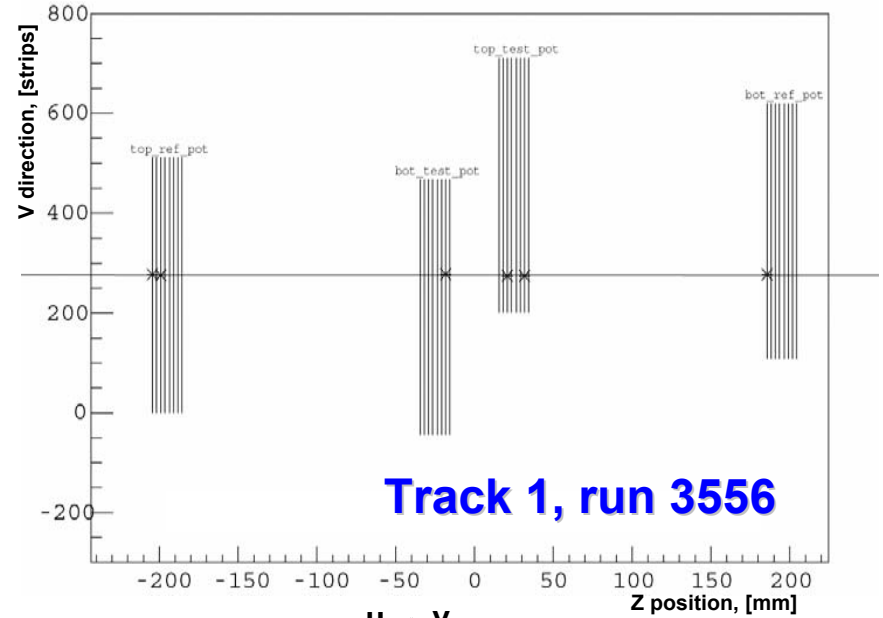


# 4.5 Track reconstruction

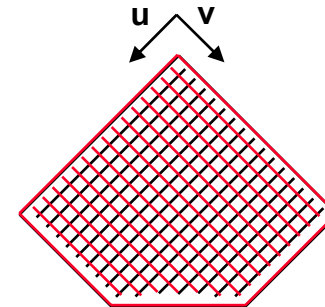
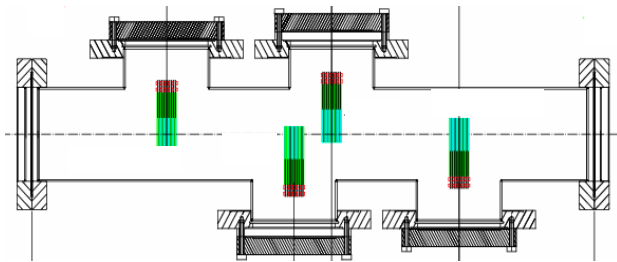
### Track u projection



### Track v projection

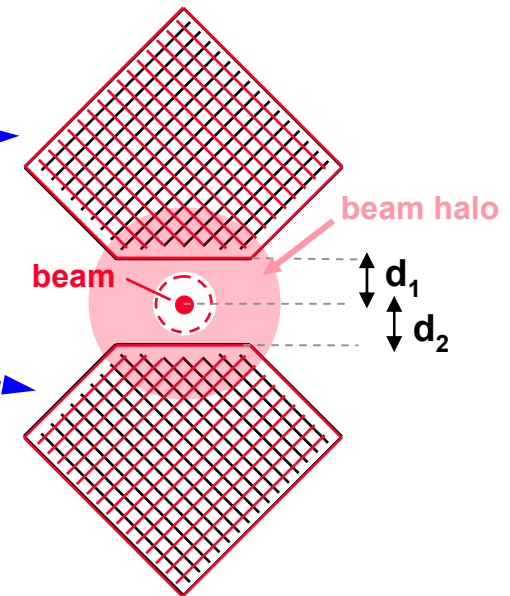
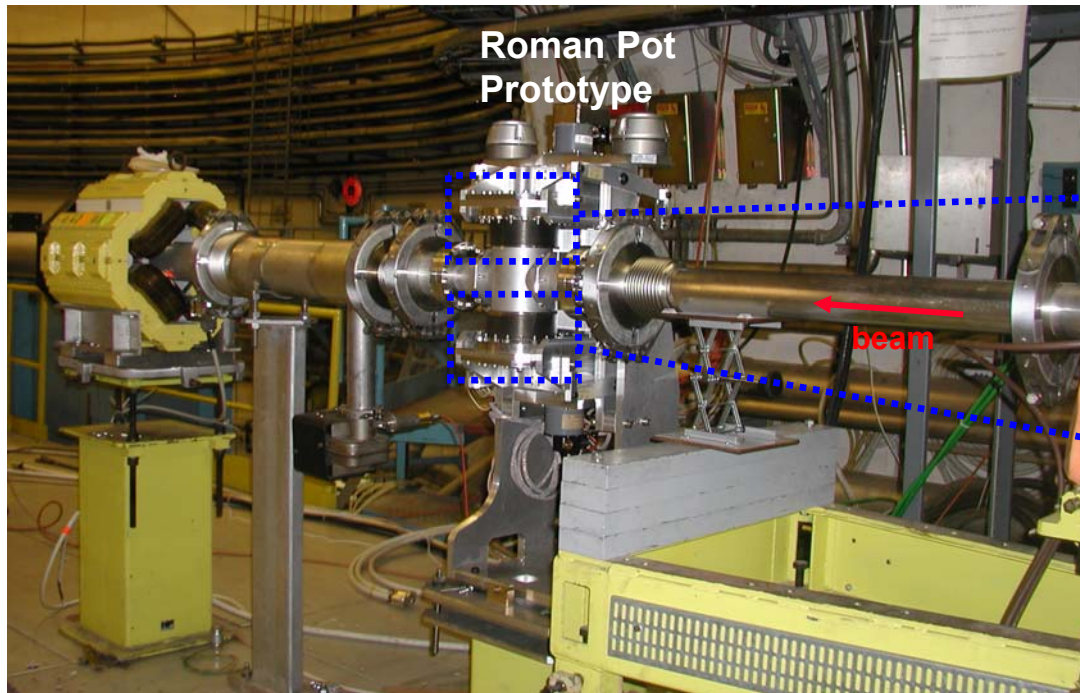


**Track 1, run 3556**





# 4.6 Full size detectors test setup in coasting beam

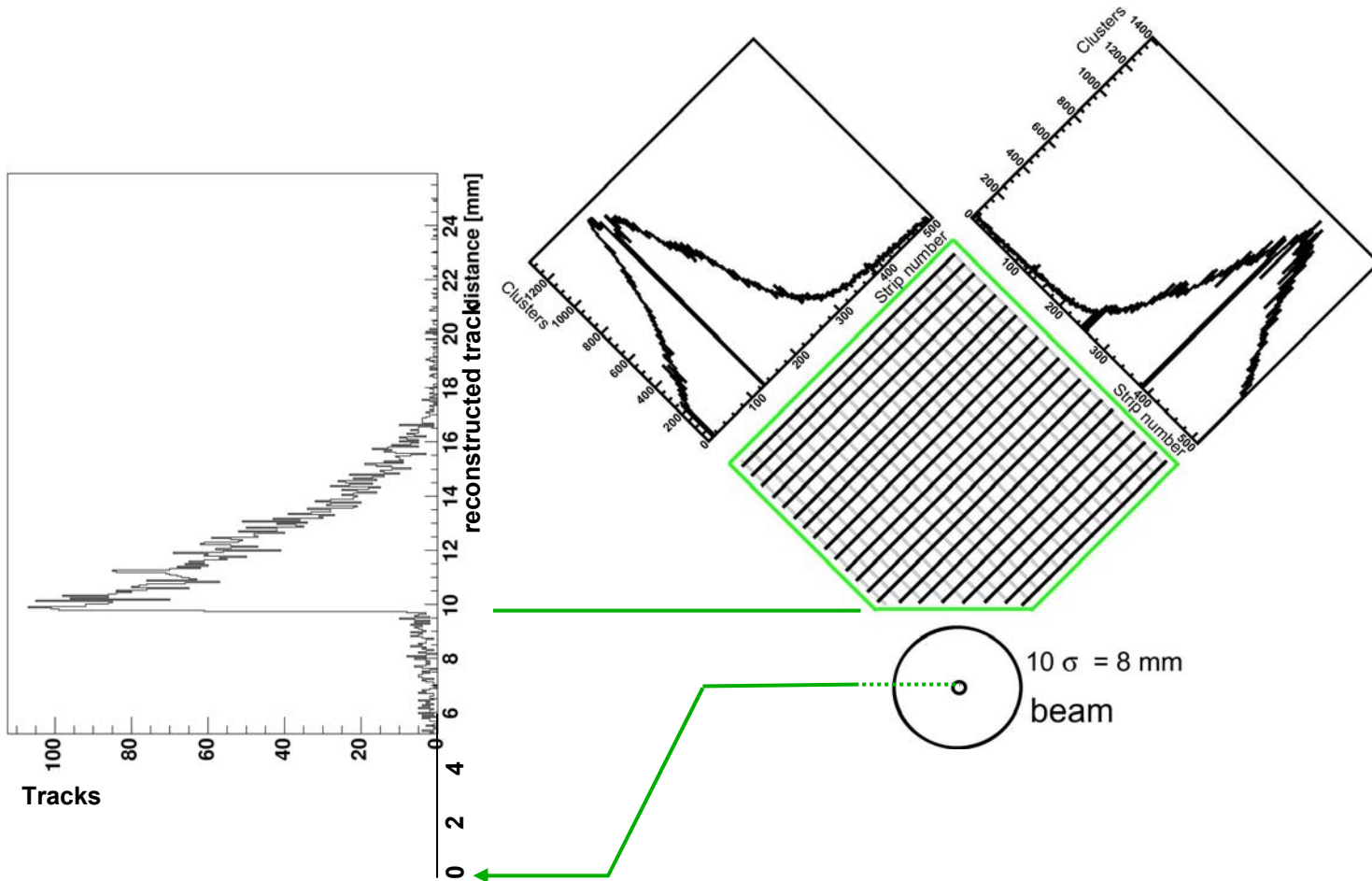


Tests of full size detectors in coasting beam:

- High energy (200 GeV) proton beam
- Beam halo particles detected for various  $d_1$ ,  $d_2$  distances
- Typical event rate of 3 kHz



# 4.7 Final Size Detector Performance in coasting beams





# 5. Conclusion

The edgeless planar detectors fulfill following criteria:

- ◆ Sensitivity up to 60  $\mu\text{m}$  from the edge
- ◆ Charge collection time below 25 ns
- ◆ Radiation hardness up to fluences of  $10^{14}$  "n"/ $\text{cm}^2$
- ◆ Operational temperature not below  $-10^\circ\text{C}$

# The TOTEM Collaboration

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